

Title (en)  
METHOD AND DEVICE FOR APPLYING A METAL COATING TO A SURFACE

Title (de)  
VERFAHREN UND VORRICHTUNG ZUR AUFBRINGUNG EINER METALLISCHEN BESCHICHTUNG AUF EINE OBERFLÄCHE

Title (fr)  
PROCÉDÉ ET DISPOSITIF D'APPLICATION D'UN REVÊTEMENT MÉTALLIQUE SUR UNE SURFACE

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Application  
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Abstract (en)  
[origin: WO2022161616A1] The invention relates to a method for applying a metal coating to a surface (8; 8') of a substrate (2; 2'), more particularly for producing conducting tracks, the method having the following steps. An ink is applied to a point of the surface (8; 8') which is to be coated, the ink having at least one metal salt of an organic acid or a mixture of such salts. Furthermore, energy is fed to the ink in order to decompose the ink, whereby the metal coating is created from the metal salt or from the metal salts. The metal coating adheres to the surface (8; 8') at the point which is to be coated. The invention also relates to a device for carrying out the method and to a corresponding ink.

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